



NOTES:

THESE SURFACES TO BE FREE OF SEAMS.

CHAMFER DENOTES PACKAGE PIN 1 ORIENTATION.

TRAY VACUUM PICKUP METHOD REQUIRES A 28mm SQUARE (MINIMUM) WALLED PICKUP AREA, LOCATED IN THE CENTER OF THE TRAY.

- N REFERS TO PACKAGE LEAD COUNTS SUPPORTED, FULLY POPULATED ARRAY 4
- 5 TOTAL USABLE CELLS $N3 = N1 \times N2$.
- PACKAGE INTERFACE CONTROLLED BY PACKAGE DESIGN AND LEAD FORM.
- NON-TABULATED DIMENSIONS HAVE A TOLERANCE OF $.X=\pm0.25$ $.XX=\pm0.15$, ANGLES ±0.5
- ALL DIMENSIONS ARE IN MILLIMETERS. 8
- INTERPRET DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ANSI Y14.5M-1982.

 $ot \Lambda$ $ilde{\Lambda}$ XXX IS THE MAXIMUM OPERATING TEMPERATURE THE EMPTY TRAY CAN BE SUBJECTED TO FOR 48 CONTINUOUS HOURS WITHOUT VIOLATING THE DIMENSIONAL TOLERANCE OF THE TRAY.



/11\ N4 INDICATES PACKAGE SIZE/LEAD COUNT ACCOMMODATED.

- 12 DIMENSIONS M, M1, M2, AND M3 DEFINE THE CENTER LINES FOR THE CELL SITES.
- 13 ALL EXTERNAL TRAY SURFACES WHICH MAY COME IN CONTACT WITH THE DRY PACK BAGS SHALL BE FREE OF SHARP EDGES.
- 14 ALL TRAY MEASUREMENTS ARE TO BE MADE WITH THE TRAY UN-RESTRICTED.
- 15 AN ADDITIONAL ROW CAN BE ADDED TO VARIATION AA. THIS ADDITIONAL ROW WOULD CHANGE N2 TO 3, N3 TO 12 MAX, AND M2 TO 30.80. THIS MIDDLE ROW CAN BE DEPOPULATED IN ANY MANNER.
- 16 THESE SCALLOPS PRESENT ON 2 X 2 MATRIX ONLY.
- 17 THESE SCALLOPS PRESENT ON 4 X 2 MATRIX ONLY.

JEDEC Solid State Product Outline	THIS REGISTERED OUTLINE COMMITTEE AND REFLECTS ELECTRONICS INDUSTRY; CI	A PRODUCT WITH	ANTICIPAT	TED USAGE IN	THE
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BALL GRID ARRAY(XBGA)

VARIATION DIMENSIONS ARE IN MILLIMETERS							
VARIATION	PACKAGE B		(LE	N (LEAD COUNT)		N1 : TRAY I	× N2 MATRIX
AA AA	7MM X 9MM X		ı	6-25-36 6-49-64		4 >	
AA AA AA AA	11MM X 13MM X 15MM X 17MM X 19MM X 19MM,18	13MM 15MM 17MM	64 10 12	9-64-100 1-100-144 0-121-196 1-169-256 5-225-289-		4) 4) 4) 4)	(2 (2 (2
AA AA AA AA	21MM X 23MM X 25MM X 27MM X 29MM X	23MM 25MM 27MM	225 250 32	5-256-400 5-324-484 6-361-576 4-441-676 1-484-784		4 > 4 > 4 > 4 > 4 >	(2 (2 (2
AB AB AB	31MM X 33MM X 33MM,32 35MM X 37.5MM X	2.5MM X 32.5MM 35MM	441-484 529	0-576-900 -625-676- 9-729-1156 5-841-1369	1024	2 > 2 > 2 > 2 >	(2 (2
AB AB	40MM X 42.5MM X		l.	5-961-1521 -1089-176)	2 2	
AA AA AB	22MM X 21MM X 25MM X 32.5MM X	18.5MM 21MM	168	119-153 3-224-340 4-304-480 5-475-744		4 > 4 > 4 > 2 >	(2 (2
JEDEC Solid Sto Product Ou	ite COMMITT	GISTERED OUTLINE EE AND REFLECTS DNICS INDUSTRY; CH	A PRODUCT	WITH ANTICI	PATED L		THE
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METRIC QUAD FLAT PACK(MQFP)

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VARIATION	DIMENSIONS	ARE	IN	MILLIMETERS

VARIATION	N4 PACKAGE BODY SIZE	N (LEAD COUNT)	N1 x N2 TRAY MATRIX
AA	5MM X 5MM	32-40	4 X 2
AA	7MM X 7MM	32-40-48-64	4 X 2
AA	10MM X 10MM	36-44-52-64-80	4 X 2
AA	12MM X 12MM	48-64-80-100	4 X 2
AA	14MM X 14MM	52-64-80-100-120	4 X 2
AA	14MM X 20MM	64-80-100-128	4 X 2
AA	20MM X 20MM	128-144-176	4 X 2
AB	24MM X 24MM	160-176-216	2 X 2
AB	28MM X 28MM	120-128-144-160-208-256	2 X 2
AB	32MM X 32MM	184-240-296	2 X 2
AB	40MM X 40MM	232-304-376	2 X 2
IEDEC		NE HAS BEEN PREPARED BY THE	

JEDEC Solid State Product Outline THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR

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PLASTIC QUAD FLAT PACK(PQFP)

	VARIATION DI	MENSIONS AR	E IN	MILLIME	TERS			
VARIATION	N4 PACKAGE BO	DY SIZE		N (LEAD CO	DUNT)			x N2 MATRIX
AA	52 Le			52			4 >	
AA	68 Le			68				< 2
AA	84 Le	ead		84	•		4 >	Κ 2
AA	100 Le			100			4 >	
AB	132 Le			132			2 >	
AB AB	164 Le 196 Le			164 196				< 2 < 2
	130 2			13.			2 ,	
JEDEC Solid State Product Outl	THIS REG COMMITTE ine ELECTRON	ISTERED OUTLINE E AND REFLECTS ICS INDUSTRY; CH	A PR	DOUCT WITH	ANTICIPAT	TED L		THE
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THIN QUAD FLAT PACK(TQFP)								
	VARIATION DIMENSIONS ARE IN MILLIMETERS							
VARIATION	N4 PACKAGE BO			N (LEAD CO	(TNUC			× N2 MATRIX
AA AA	5MM X 7MM X			32- 32-40-				X 2 X 2
AA AA AA	10MM X 12MM X 14MM X 14MM X	12MM 14MM		36-44-52 44-52-64 52-64-80-	-80-100 -100-120		4 1	X 2 X 2 X 2 X 2
AA AB AB	20MM X 24MM X 28MM X	24MM		144 176 160208	216		2	X 2 X 2 X 2
JEDEC	THIS REG	SISTERED OUTLINE	HAS	BEEN PREP	ARED BY	THE	JC-11	
Solid Stat Product Out	e COMMITTE	E AND REFLECTS NICS INDUSTRY; CH	A PR	ODUCT WITH	ANTICIPAT	red us		THE
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THIN SMALL OUTLINE PACKAGE (TSOP TYPE I)

	VARIATION DIMENSIONS AR	E IN MILLIMETERS	
VARIATION	N4 PACKAGE BODY SIZE	N (LEAD COUNT)	N1 × N2 TRAY MATRIX
AA	6MM X 14MM	24	4 X 2
AA	6MM X 16MM	24	4 X 2
AA	6MM X 18MM	24	4 X 2
AA	6MM X 20MM	24	4 X 2
AA	8MM X 14MM	32	4 X 2
AA	8MM X 16MM	32	4 X 2
AA	8MM X 18MM	32	4 X 2
AA	8MM X 20MM	32	4 X 2
AA	10MM X 14MM	40	4 X 2
AA	10MM X 16MM	40	4 X 2
AA	10MM X 18MM	40	4 X 2
AA	10MM X 20MM	40	4 X 2
AA	12MM X 14MM	48	4 X 2
AA	12MM X 16MM	48	4 X 2
AA	12MM X 18MM	48	4 X 2
AA	12MM X 20MM	48	4 X 2
IEDEO	THIS DECISTEDED OUTLINE	HAS BEEN PREPARED BY TH	HF 10-11
JEDEC Solid State Product Outl		A PRODUCT WITH ANTICIPATED ANGES ARE LIKELY TO OCCUP	USAGE IN THE
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THIN SMALL OUTLINE PACKAGE (TSOP TYPE II)

	VARIATION D	IMENSIONS AR	E IN MI	LLIME	TERS			
VARIATION	N4 PACKAGE BC	DDY SIZE	(LI	N EAD CO	OUNT)			x N2 MATRIX
AA AA AA AA	.300" .400" .400" 12.70MM		2	20-24 8-40- 32-50	1-26 44/40		4 4 4 4	MATRIX X 2 X 2 X 2 X 2 X 2
JEDEC Solid State Product Outl	THIS REG COMMITTE	ISTERED OUTLINE E AND REFLECTS A IICS INDUSTRY; CH	PRODUC	HTM T	ANTICIPAT	ED US		THE
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	VARIATION DIMENSI	ONS AR	E IN MILLIMETERS	
S _{YMBOL}	DIMENSIONS ARE IN MILLIMETERS	NOT_	DIMENSIONS ARE IN MILLIMETERS	NOT
M _B	_ AA		AB	
	MIN NOM MAX	E.	MIN NOM MAX	'E
М	21.75 BSC	12	29.20 BSC	12
M1	22.15 BSC	12	31.15 BSC	12
M2	63.60 BSC	12	45.60 BSC	12
мз	30.80 BSC	12	77.50 BSC	12
N1	4 COLUMNS		2 COLUMNS	
N2	2 ROWS	15	2 ROWS	
N3	8	5	4	5
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